

ABSTRACT

To realize a laser irradiation apparatus by using which accuracy in processing a substrate can be improved. A laser irradiation apparatus (1) according to an embodiment includes a laser irradiation unit (3) configured to apply laser light (L1) to a substrate (S), a base part (4), and a conveyance stage (5) configured to convey the substrate (S). The conveyance stage (5) includes a stage (10) configured to be movable over the base part (4), a base flange (11) fixed over the stage (10), a substrate stage (12) fixed to an upper end part of the base flange (11) and configured so that the substrate (S) is placed thereover, and a pusher pin (13) for supporting the substrate, the pusher pin being configured to penetrate the substrate stage (12) and to be movable up and down.

[Fig. 1]